XN04130 (XN4130)

Silicon PNP epitaxial planer transistor

For amplification of low frequency output

Features

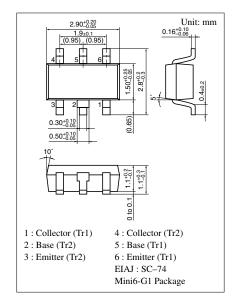
- Two elements incorporated into one package. (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half.

Basic Part Number of Element

• UNR1130(UN1130) × 2 elements

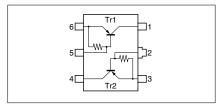
Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Ratings	Unit	
Rating of element	Collector to base voltage	V_{CBO}	-15	V	
	Collector to emitter voltage	V_{CEO}	-15	V	
	Emitter to base voltage	V_{EBO}	-7	V	
	Collector current	I_{C}	- 0.5	A	
	Peak collector current	I_{CP}	-1	A	
Overall	Total power dissipation	P_{T}	300	mW	
	Junction temperature	T_{j}	150	°C	
	Storage temperature	T_{stg}	-55 to +150	°C	



Marking Symbol: OF

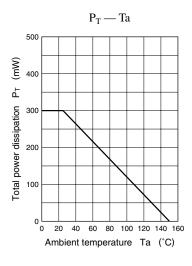
Internal Connection

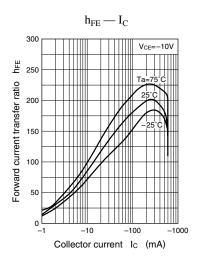


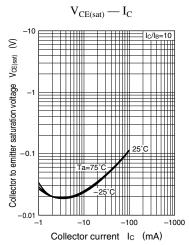
Electrical Characteristics (Ta=25°C)

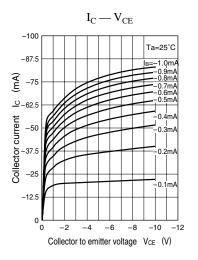
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector to base voltage	V _{CBO}	$I_{\rm C} = -10\mu A, I_{\rm E} = 0$	-15			V
Collector to emitter voltage	V _{CEO}	$I_{\rm C} = -1 \text{mA}, I_{\rm B} = 0$	-15			V
Emitter to base voltage	V _{EBO}	$I_{\rm E} = -1 \text{mA}, I_{\rm C} = 0$	-7			V
Collector cutoff current	I_{CBO}	$V_{CB} = -10V, I_E = 0$			- 0.1	μΑ
Forward current transfer ratio	h _{FE1}	$V_{CE} = -2V, I_C = -500 \text{mA}*$	80		280	
Forward current transfer ratio	h _{FE2}	$V_{CE} = -2V, I_C = -1A*$	50			
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = -300 \text{mA}, I_B = -6 \text{mA}$		- 0.2	- 0.3	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_C = -300 \text{mA}, I_B = -6 \text{mA}$		- 0.9	-1.3	V
Transition frequency	f_T	$V_{CB} = -10V$, $I_E = 50mA$, $f = 200MHz$		130		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -10V$, $I_E = 0$, $f = 1MHz$		22		pF
Base to emitter resistance	R _{BE}		-30%	10	+30%	kΩ

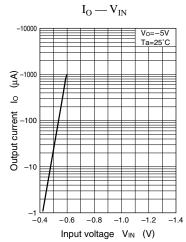
*Pulse measurement

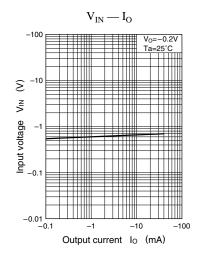


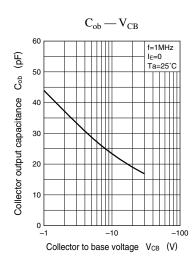












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